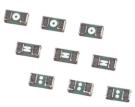




# TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses FF Series (Very Fast Acting), 0402 Size



### **Clearing Time Characteristics:**

% of Current Rating	Ampere Rating	Opening Time at 25°C
100%	0.200A-5.00A	4 hours min.
200%	0.375A-5.00A	5 seconds max.
2000/	0.200A-0.250A	5 seconds max.
300%	0.375A-5.00A	0.2 second max.

#### **Agency Approval:**

Recognized Under the Components Program of UL. File Number: E232989.

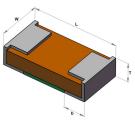
### Features:

- Very fast acting
- Low DCR

- High inrush current withstanding capability Fiberglass enforced epoxy fuse body Copper termination with nickel and tin plating Halogen free, RoHS compliance and lead-free

### Shape and Dimensions:

Unit	Inch	mm
Length (L)	0.039± 0.004	1.00 ± 0.10
Width (W)	0.020 ± 0.004	0.51± 0.10
Thickness (T)	0.013 ± 0.004	0.33 ± 0.10
Termination bandwidth (b)	0.012 ± 0.004	0.30 ± 0.10



### **Typical Ratings and Characteristics:**

Operating temperature: -55 to +90°C

Part Number	Current Rating (A)	Voltage Rating (VDC)	Interrupting Rating	Nominal Cold DCR (Ω)1	Nominal I <sup>2</sup> t (A2s)2	Marking
T0402FF0200TM	0.200	35		0.60	0.0017	••
T0402FF0250TM	0.250	35		0.33	0.0035	:
T0402FF0375TM	0.375	35		0.24	0.0036	•••
T0402FF0500TM	0.50	35		0.16	0.0060	
T0402FF0750TM	0.75	35		0.10	0.012	
T0402FF1000TM	1.00	35		0.073	0.024	+
T0402FF1250TM	1.25	35		0.054	0.045	×
T0402FF1500TM	1.50	35	35A@35V DC	0.040	0.081	I
T0402FF1750TM	1.75	35		0.034	0.092	
T0402FF2000TM	2.00	35		0.031	0.12	
T0402FF2500TM	2.50	35		0.018	0.22	H
T0402FF3000TM	3.00	35		0.015	0.27	III
T0402FF3500TM	3.50	35		0.012	0.34	H
T0402FF4000TM	4.00	35		0.011	0.36	
T0402FF5000TM	5.00	35		0.0090	0.55	0

<sup>1</sup> Measured at ≤ 10% of rated current and 25°C ambient.

<sup>2</sup> Melting I<sup>2</sup>t at 0.001 second of current rating.

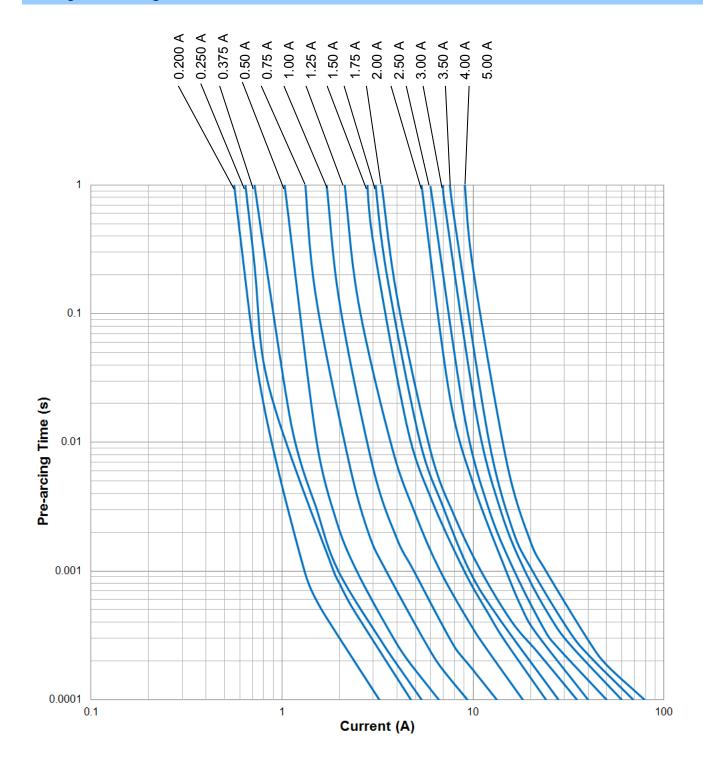




Revision of May 2019

# **TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses** FF Series (Very Fast Acting), 0402 Size

## Average Pre-arcing Time Curves:



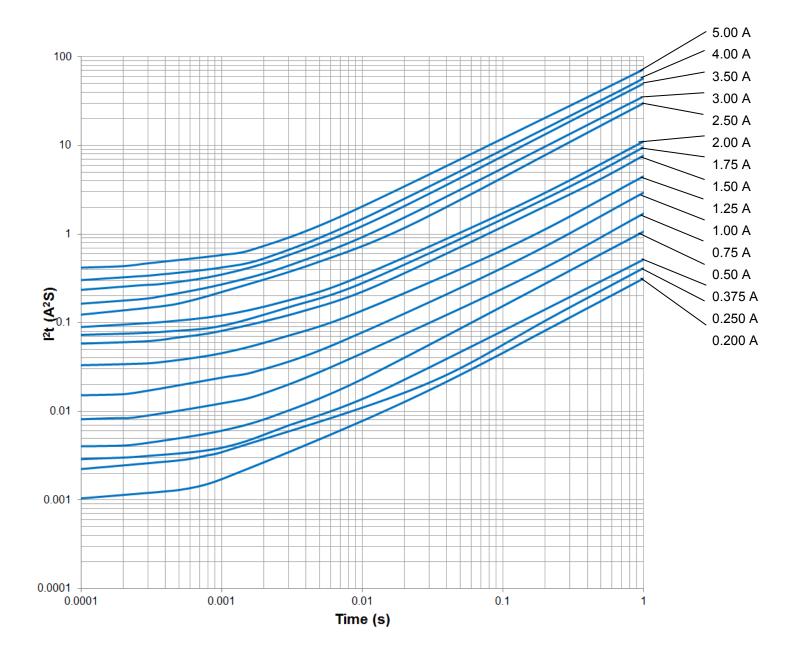




Revision of May 2019

# **TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses** FF Series (Very Fast Acting), 0402 Size

# Average l<sup>2</sup>t vs. t Curves:







# **TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses**

### **Product Identification:**

- <u>T 0603 FF 1000 T M</u>
- (1) (2) (3) (4) (5) (6)
- (1) Product Code: T-Thin Film
- (2) Size Code: Standard EIA chip sizes
- (3) Series Code: FF—Very Fast Acting, HI—High Inrush
- (4) Current Rating Code: 0500-0.5A, 1000-1.0A
- (5) Package Code: T—Tape & Reel; B—Bulk

#### **Environmental Tests:**

No.	Test item	Requirement	Test condition	Reference
1	Bending	≤1A: 10% DCR change max. >1A: 20% DCR change max.	2mm	Refer to AEM QIQ034
2	Solderability	95% coverage min.	One dip at 255 $^\circ\!\!\mathbb{C}$ for 5 seconds	MIL-STD-202 Method 208
3	Thermal shock	DCR change within ±10% No mechanical damage	100 cycles between -55°C and +125°C	MIL-STD-202 Method 107
4	Moisture resistance	DCR change within ±10% No excessive corrosion	10 cycles	MIL-STD-202 Method 106
5	Salt spray	DCR change within $\leqslant \pm 10\%$ No excessive corrosion	5% salt solution, 48 hour exposure	MIL-STD-202 Method 101
6	Mechanical vibration	DCR change within $\leqslant \pm 10\%$ No mechanical damage	0.4" D.A. or 30G between 5 and 3000 Hz	MIL-STD-202 Method 204
7	Mechanical shock	DCR change within $\leqslant \pm 10\%$ No mechanical damage	1500G, 0.5 ms, half sine shocks	MIL-STD-202 Method 213
8	Life	Change of voltage drop within ±10%, no open circuit	75% rated current, 2000 hours, ambient temperature +20°C to 30°C	

## Packaging:

Chip Size	Parts on 7 inch (178mm) Reel			
0603(1608)	8,000			
0402(1005)	20,000			

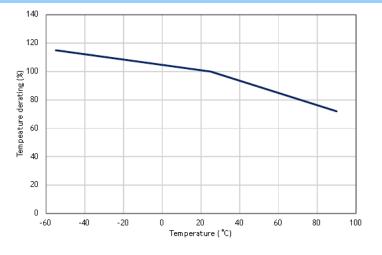




Revision of May 2019

# TF-FUSE<sup>®</sup> Thin Film Surface Mount Fuses

### **Temperature Effect on Current Rating:**



# **Recommended Reflow Soldering Profile:**

Profile Feature	Pb-Free Assembly		<b>Т</b> р-	
Preheat/Soak Temperature Min (T <sub>smin</sub> ) Temperature Max(T <sub>smax</sub> ) Time(t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	150°C 200°C 60~120 seconds	ture 🗔	T <sub>L</sub> -	$T_{smax}$
Ramp-uprate ( $T_L$ to $T_p$ )	3°C/second max.	era		
Liquidous temperature( $T_L$ ) Time( $t_L$ ) maintained above $T_L$	217°C 60~150 seconds	e m p		$\xrightarrow{T_{smin}}$
Peak package body temperature (T <sub>p</sub> )	260°C	F		· / · · ·
Time $(t_p)^*$ within 5°C of the specified classification temperature $(T_c)$	30 seconds *		25	Time 25°C to Peak
Ramp-down rate $(T_p \text{ to } T_L)$	6°C/second max.	]		Time ⇔
Time 25°C to peak temperature	8 minutes max.			
$^{\ast}$ Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum		1		

#### Thermal Shock When Making Correction with a Soldering Iron:

The temperature of solder iron tip should be controlled under 350°C and soldering time should be less than 3 sec. The soldering iron tip should not directly touch the top side termination of the component.







# Disclaimer

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